

**Operation:** SMT+DIP 沉板式 & 3.1Type-C 连接器/防水结构



**LTEM NO.:** MC-313F-14 (Consumer Electronics)

(9.65L×9.20W×4.00H & DUL SMT LOW PCB TYPE)

## Universal Serial Bus Connectors



### Technical parameter

外焊 SMT+DIP

PROJECT	LEVEL	A[better product]	B[average product]
		CONTACT RATING	3A, 24V DC
Electrical Properties	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut
Durable Performance	There No Load	6,500 Cycles	5,500 Cycles
	Rated Load	5,500 Cycles	4,500 Cycles
Storage temp.		-25℃~+75℃(Operating Temp: )	

側向導入 LATERAL

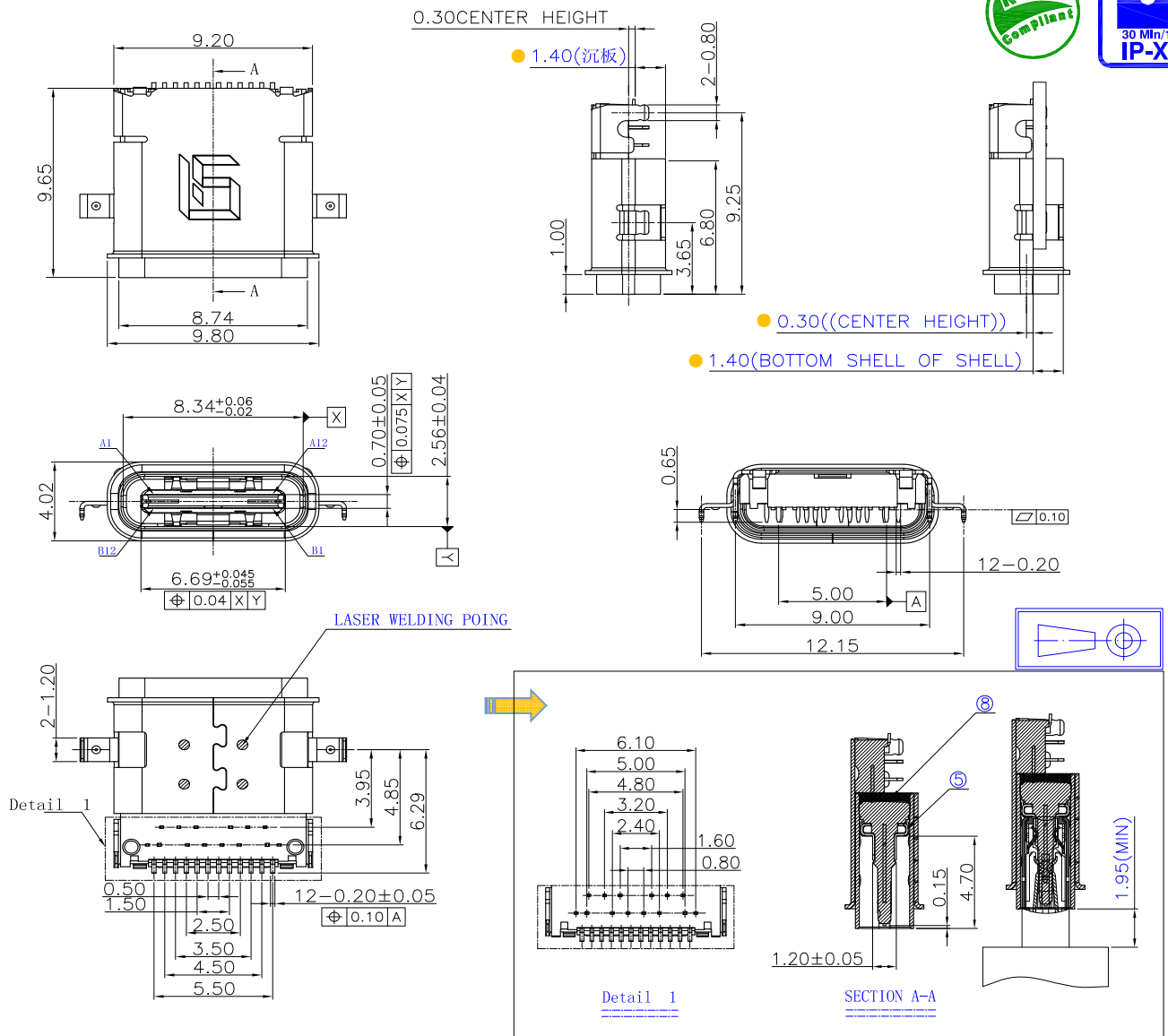
精密部品 NICETY

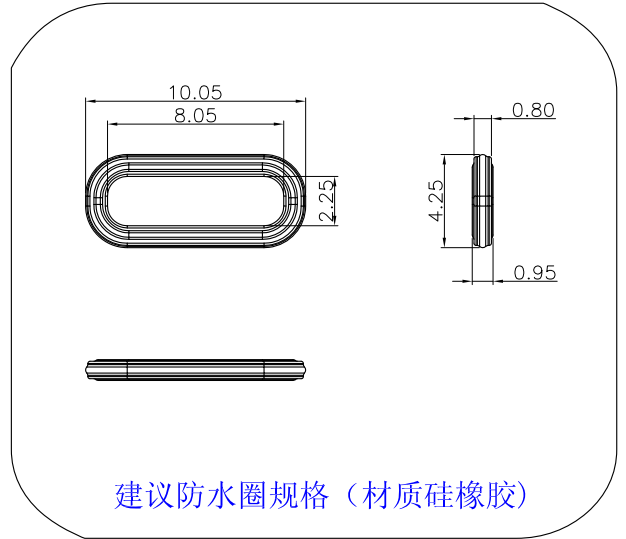
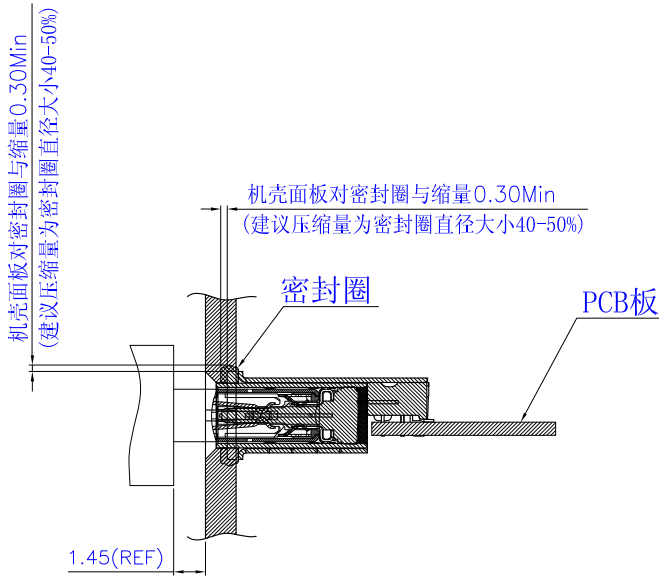
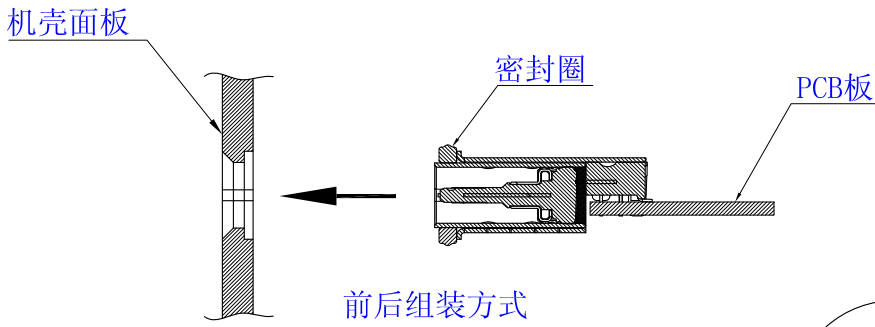
可靠 STABILIZE

環保材質 RoHS

Page1

Unit:mm





组装面板后公母头对插示意图

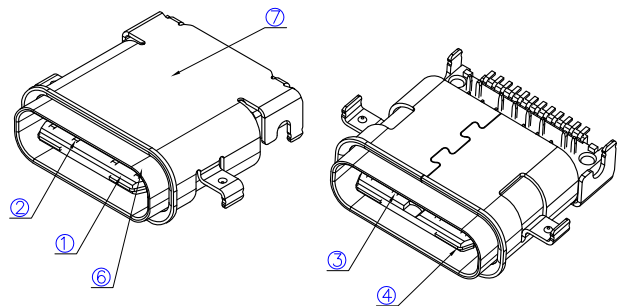


SPECIFIED TOLERANCES

UNLESS OTHERWISE



DECIMALS	ANGLES
X.X :±0.25	X.X :±3°
X.XX :±0.15	X.XX :±2°
X.XXX :±0.10	



Material declaration			
No.	NAME	MATERIAL	DESCRIPTION
① A	HOUSING	-	HIGH TEMP[Black]
② B	Terminal-A 12PIN	COPPER ALLOY 【G/F】	Au:15 μ" PLATING OVERALL;[t=0.12mm] 铜镍硅合金
③ C	Terminal-B 12PIN	COPPER ALLOY 【G/F】	Au:15 μ" PLATING OVERALL;[t=0.12mm] 铜镍硅合金
④ D	MID PLATE	STAINLESS 【G/F】	STAINLESS STEEL(t=0.15mm)
⑤ E	GND PLATE	STAINLESS 【G/F】	STAINLESS STEEL/ Ni PLATING(t=0.10mm)
⑥ F	SHELL-#1	STAINLESS 【G/F】	STAINLESS STEEL/ Ni PLATING(t=0.20mm)
⑦ G	SHELL-#2	STAINLESS 【G/F】	STAINLESS STEEL/ Ni PLATING(t=0.20mm)
⑧ H	GLUE WATER	-	EPOXY[Black]

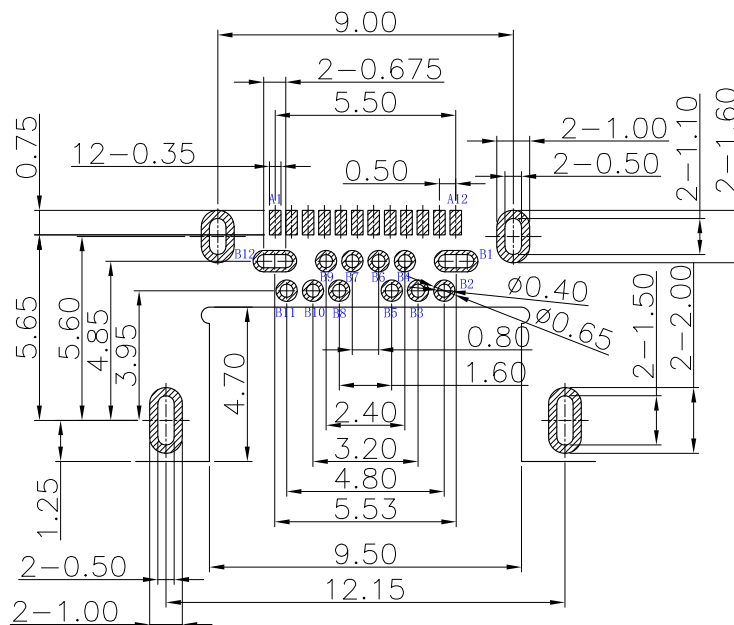
**Operating Force**

Inward  
Exiting

5.0~8.0N. (1N.=100gram-force)  
5.0~8.0N. (1N.=100gram-force)

**Solder-ability (Max.)**

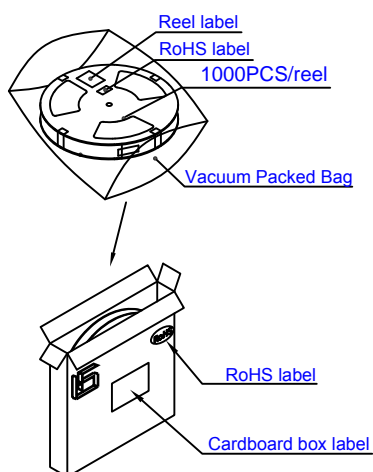
IR Reflow:255°C, 5sec. Manual:350°C, 3sec.



Tolerance:±0.05,Thickness=0.60mm

**PIN ASSIGNMENTS**

PIN	Signal NAME	Description	PIN	Signal NAME	Description
A 1	GND	Ground return	B12	GND	Ground return
A 2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A 3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A 4	V BUS	Bus Power	B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel	B 8	SBU2	Sideband Use (SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use (SBU)	B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power	B 4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B 3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B 2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B 1	GND	Ground return



**注記 NOTICE**

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